

We claim:

1. A method for forming an integrated circuit capacitor,  
comprising:

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forming a dielectric region in a semiconductor substrate;

forming a patterned polysilicon layer on said dielectric  
region;

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forming a dielectric layer over said polysilicon layer;

forming a conductive layer over said dielectric layer;

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forming a hardmask layer over said conductive layer;

etching said hardmask layer and partially etching said  
conductive layer using a dry etch process; and

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etching remaining conductive layer using a wet etch  
process.

2. The method of claim 1 wherein said dry etch process used to  
etch said hardmask layer and partially etch said conductive

layer is a two step etch process consisting essentially of a first plasma etch step and a second plasma etch step.

3. The method of claim 2 wherein said first plasma etch step is  
5 a plasma etch process comprising  $\text{Cl}_2$ , Ar, and  $\text{BCl}_3$ .
4. The method of claim 3 wherein said second plasma etch step is a plasma etch process comprising  $\text{Cl}_2$ , Ar,  $\text{BCl}_3$ , and  $\text{N}_2$ .
- 10 5. The method of claim 1 wherein said wet etch process is a two step etch process consisting essentially of a first wet etch step and a second wet etch step.
6. The method of claim 5 wherein said first wet etch step  
15 comprises spraying a Piranha solution and a  $\text{SCl}$  solution.
7. The method of claim 6 wherein said second wet etch step comprises a  $\text{SCl}$  megasonic process.

8. A method for forming a high precision integrated circuit capacitor, comprising:

5       forming a dielectric region in a semiconductor substrate;

forming a patterned polysilicon layer on said dielectric region;

10       forming a metal silicide on said polysilicon layer;

forming a dielectric layer over said metal silicide layer;

forming a TiN layer over said dielectric layer;

15       forming a silicon oxide layer over said conductive layer;

etching said silicon layer and partially etching said TiN layer using a two step plasma etch process; and

20       etching remaining TiN layer using a two step wet etch process.

9. The method of claim 8 wherein said two step etch process consists essentially of a first plasma etch step and a second plasma etch step.

5 10. The method of claim 9 wherein said first plasma etch step is a plasma etch process comprising  $\text{Cl}_2$ , Ar, and  $\text{BCl}_3$ .

11. The method of claim 10 wherein said second plasma etch step is a plasma etch process comprising  $\text{Cl}_2$ , Ar,  $\text{BCl}_3$ , and  $\text{N}_2$ .

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12. The method of claim 8 wherein said wet etch process consists essentially of a first wet etch step and a second wet etch step.

15 13. The method of claim 12 wherein said first wet etch step comprises spraying a Piranha solution and a  $\text{SCl}$  solution.

14. The method of claim 13 wherein said second wet etch step comprises a  $\text{SCl}$  megasonic process.

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15.A method for forming an integrated circuit capacitor in a trench, comprising:

forming a trench in a semiconductor substrate;

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forming a first dielectric layer in said trench;

forming a patterned polysilicon layer on said dielectric layer;

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forming a metal silicide on said polysilicon layer;

forming a second dielectric layer over said metal silicide layer;

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forming a conductive layer over said dielectric layer;

forming a hardmask layer over said conductive layer;

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etching said hardmask layer and partially etching said conductive layer using a dry etch process; and

etching remaining conductive layer using a wet etch process.

16.The method of claim 15 wherein said dry etch process used to etch said hardmask layer and partially etch said conductive layer is a two step etch process consisting essentially of a first plasma etch step and a second plasma etch step.

17.The method of claim 16 wherein said first plasma etch step is a plasma etch process comprising  $\text{Cl}_2$ , Ar, and  $\text{BCl}_3$ .

18.The method of claim 17 wherein said second plasma etch step is a plasma etch process comprising  $\text{Cl}_2$ , Ar,  $\text{BCl}_3$ , and  $\text{N}_2$ .

19.The method of claim 15 wherein said wet etch process is a two step etch process consisting essentially of a first wet etch step and a second wet etch step.

20.The method of claim 19 wherein said first wet etch step comprises spraying a Piranha solution and a  $\text{SCl}$  solution.

21.The method of claim 20 wherein said second wet etch step comprises a  $\text{SCl}$  megasonic process.